

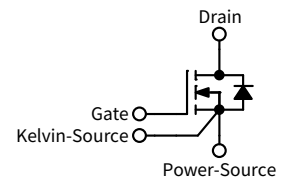
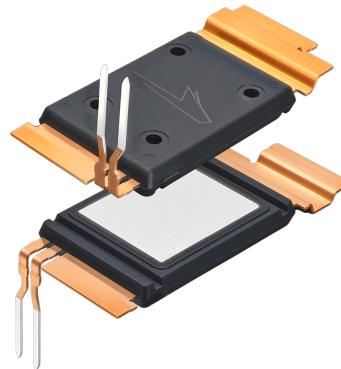
# EDB010M12TM4, EDB010M12TM4L

Automotive 1200 V, 9.3 mΩ, Silicon Carbide, Single Switch Power Module

|                           |               |
|---------------------------|---------------|
| <b>V<sub>DS</sub></b>     | <b>1200 V</b> |
| <b>R<sub>DS(on)</sub></b> | <b>9.3 mΩ</b> |

## Technical Features

- AQG 324 Qualified
- Soft Body Diode Recovery
- Baseplateless Module with High Performance Si<sub>3</sub>N<sub>4</sub> Insulator
- Laser Weldable Power Terminals
- Sinterable and Solderable Backside (Silver Plated)
- Solderable Signal Pins (Silver Plated)
- Package with Extended Creepage
- Comparative Tracking Index (CTI) > 600 (Material Group I)
- Limited Extended Operation (T<sub>VJ(op)</sub> = 200 °C for 100 h)



## Typical Applications

- Automotive Traction Inverters

## System Benefits

- Ultra-Low Loss
- High Performance in a small Footprint
- Design Flexibility
- Enables high Reliability Interconnects

## Maximum Parameters (Verified by Design)

| Parameter                          | Symbol               | Min. | Typ.   | Max. | Unit | Conditions   | Note    |
|------------------------------------|----------------------|------|--------|------|------|--|---------|
| Drain-Source Voltage               | V <sub>DS</sub>      |      |        | 1200 | V    |  |         |
| Gate-Source Voltage, Maximum Value | V <sub>GS(max)</sub> | -8   |        | +19  |      | Transient  | Note 1  |
| Gate-Source Voltage, Recommended   | V <sub>GS(op)</sub>  |      | -4/+15 |      |      | Static   | Fig. 27 |
| DC Continuous Drain Current        | I <sub>D</sub>       |      | 160    |      | A    | V <sub>GS</sub> = 15 V, T <sub>C</sub> = 100 °C,<br>T <sub>VJ</sub> = 175 °C | Note 2  |
| Virtual Junction Temperature       | T <sub>VJ(op)</sub>  | -40  |        | 175  | °C   | Continuous operation   |         |
|                                    |                      |      |        | 200  |      | 100 hours over lifetime  |         |
| Sinter Temperature                 | T <sub>L</sub>       |      | 230    |      |      |  |         |
| Sinter Pressure                    | P <sub>S</sub>       |      | 14     |      | Mpa  |  |         |

Note (1): Recommended turn-on gate voltage is 15 V with ±5 % regulation tolerance

Note (2): Current limit calculated by  $I_{D(max)} = \sqrt{(P_D/R_{DS(typ)}(T_{VJ(max)}))}$  where  $P_D = (T_{VJ} - T_C)/R_{th(JC,typ)}$



### MOSFET Characteristics ( $T_{VJ} = 25\text{ °C}$ Unless Otherwise Specified)

| Parameter                                       | Symbol        | Min. | Typ. | Max. | Unit                     | Conditions  | Note                     |
|---|---------------|------|------|------|--------------------------|---|--------------------------|
| Drain-Source Breakdown Voltage                  | $V_{(BR)DSS}$ | 1200 |      |      |                          | $V_{GS} = 0\text{ V}$ , $T_{VJ} = -40\text{ °C}$  |                          |
| Gate Threshold Voltage                          | $V_{GS(th)}$  | 1.8  | 2.5  | 3.6  | V                        | $V_{DS} = V_{GS}$ , $I_D = 30\text{ mA}$  | Fig. 10                  |
|   |               |      | 2.0  |      |                          | $V_{DS} = V_{GS}$ , $I_D = 30\text{ mA}$ , $T_{VJ} = 175\text{ °C}$                                       |                          |
| Zero Gate Voltage Drain Current                 | $I_{DSS}$     |      | 2    | 64   | $\mu\text{A}$            | $V_{GS} = 0\text{ V}$ , $V_{DS} = 1200\text{ V}$  |                          |
| Gate-Source Leakage Current                     | $I_{GSS}$     |      | 20   | 200  | nA                       | $V_{GS} = 15\text{ V}$ , $V_{DS} = 0\text{ V}$  |                          |
| Drain-Source On-State Resistance (Devices Only) | $R_{DS(on)}$  |      | 9.3  | 12.5 | m $\Omega$               | $V_{GS} = 15\text{ V}$ , $I_D = 110\text{ A}$   | Note 3<br>Figs. 2, 3     |
|   |               |      | 18.3 | 22.3 |                          | $V_{GS} = 15\text{ V}$ , $I_D = 110\text{ A}$ , $T_{VJ} = 175\text{ °C}$                                  |                          |
|   |               |      | 20.7 |      |                          | $V_{GS} = 15\text{ V}$ , $I_D = 110\text{ A}$ , $T_{VJ} = 200\text{ °C}$                                  |                          |
| Transconductance                                | $g_{fs}$      |      | 95   |      | S                        | $V_{DS} = 20\text{ V}$ , $I_D = 110\text{ A}$   | Fig. 4                   |
|   |               |      | 94   |      |                          | $V_{DS} = 20\text{ V}$ , $I_D = 110\text{ A}$ , $T_{VJ} = 175\text{ °C}$                                  |                          |
| Turn-On Switching Energy                        | $E_{ON}$      |      | 3.3  |      | mJ                       | $T_{VJ} = 25\text{ °C}$   | Figs. 11, 12, 13, 24, 25 |
|   |               |      | 4.4  |      |                          | $T_{VJ} = 175\text{ °C}$  |                          |
|   |               |      | 4.9  |      |                          | $T_{VJ} = 200\text{ °C}$  |                          |
| Turn-Off Switching Energy                       | $E_{OFF}$     |      | 1.5  |      | $T_{VJ} = 25\text{ °C}$  |   |                          |
|   |               |      | 1.5  |      | $T_{VJ} = 175\text{ °C}$ |   |                          |
|   |               |      | 1.6  |      | $T_{VJ} = 200\text{ °C}$ |   |                          |
| Internal Gate Resistance                        | $R_{G(int)}$  |      | 1.5  |      | $\Omega$                 | $f = 100\text{ kHz}$ , $V_{AC} = 250\text{ mV}$   |                          |
| Input Capacitance                               | $C_{iss}$     |      | 9.9  |      | nF                       | $V_{GS} = 0\text{ V}$ , $V_{DS} = 800\text{ V}$ ,<br>$V_{AC} = 250\text{ mV}$ , $f = 100\text{ kHz}$      | Fig. 9                   |
| Output Capacitance                              | $C_{oss}$     |      | 0.33 |      |                          |   |                          |
| Reverse Transfer Capacitance                    | $C_{rss}$     |      | 27   |      |                          |   |                          |
| Gate to Source Charge                           | $Q_{GS}$      |      | 106  |      | nC                       | $V_{DS} = 800\text{ V}$ , $V_{GS} = -4\text{ V}/15\text{ V}$ ,<br>$I_D = 110\text{ A}$ , per IEC60747-8-4 |                          |
| Gate to Drain Charge                            | $Q_{GD}$      |      | 100  |      |                          |   |                          |
| Total Gate Charge                               | $Q_G$         |      | 374  |      |                          |   |                          |
| Thermal Resistance, Junction to Case            | $R_{th(JC)}$  |      | 0.15 |      | K/W                      |   | Fig. 16                  |

Note (3): Total effective resistance = MOSFET  $R_{DS(on)}$  + package resistance



### Diode Characteristics ( $T_{VJ} = 25\text{ }^{\circ}\text{C}$ Unless Otherwise Specified)

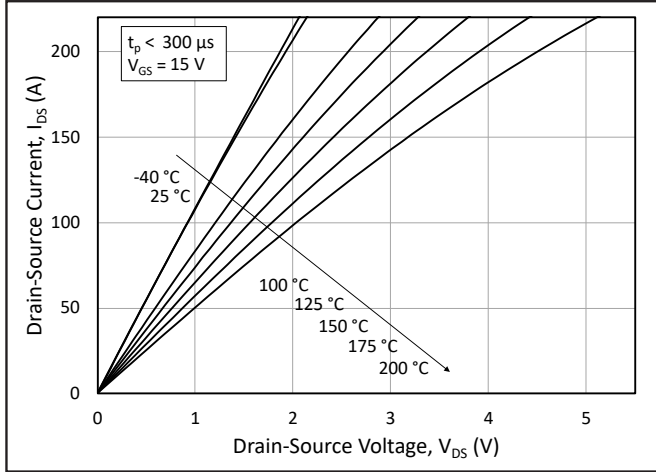
| Parameter                                 | Symbol    | Min. | Typ. | Max. | Unit          | Conditions   | Note   |
|---|-----------|------|------|------|---------------|--|--|
| Body Diode Forward Voltage (Devices Only) | $V_{SD}$  |      | 5.9  |      | V             | $V_{GS} = -4\text{ V}, I_{SD} = 110\text{ A}$  | Fig. 7   |
|   |           |      | 5.2  |      |               | $V_{GS} = -4\text{ V}, I_{SD} = 110\text{ A}, T_{VJ} = 175\text{ }^{\circ}\text{C}$  |  |
| Reverse Recovery Time                     | $t_{RR}$  |      | 98   |      | ns            | $V_{GS} = -4\text{ V}, I_{SD} = 150\text{ A}, V_R = 800\text{ V}, di/dt = 8.3\text{ A/ns}, T_{VJ} = 175\text{ }^{\circ}\text{C}$ | Fig. 26  |
| Reverse Recovery Charge                   | $Q_{RR}$  |      | 2.8  |      | $\mu\text{C}$ |  |  |
| Peak Reverse Recovery Current             | $I_{RRM}$ |      | 76   |      | A             |  |  |
| Reverse Recovery Energy                   | $E_{RR}$  |      | 0.3  |      | mJ            | $T_{VJ} = 25\text{ }^{\circ}\text{C}$  | Figs. 11, 12, 13, 14, 26<br>$V_{DS} = 800\text{ V}, I_D = 150\text{ A}, V_{GS} = -4\text{ V}/15\text{ V}, R_{G(ON)} = 3\text{ }\Omega, L_G = 18.3\text{ nH}$ |
|   |           |      | 2.2  |      |               | $T_{VJ} = 175\text{ }^{\circ}\text{C}$   |  |
|   |           |      | 2.7  |      |               | $T_{VJ} = 200\text{ }^{\circ}\text{C}$   |  |

### Module Physical Characteristics

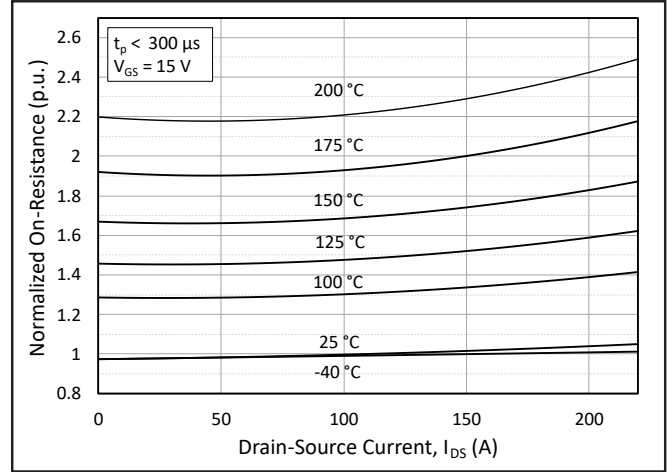
| Parameter                  | Symbol      | Min. | Typ. | Max. | Unit               | Conditions                                 | Note                  |        |
|----------------------------|-------------|------|------|------|--------------------|--|-----------------------|--------|
| Package Resistance         | $R_{pkg}$   |      | 0.17 |      | m $\Omega$         | $T_C = 25\text{ }^{\circ}\text{C}$         | Drain to power-source | Note 3 |
|                            |             |      | 0.27 |      |                    | $T_C = 175\text{ }^{\circ}\text{C}$        |                       |        |
| Stray Inductance           | $L_{stray}$ |      | 6.6  |      | nH                 | Drain to power-source, $f = 10\text{ MHz}$ |                       |        |
| Storage Temperature        | $T_{stg}$   | -40  |      | 125  | $^{\circ}\text{C}$ |  |                       |        |
| Weight                     | W           |      | 8.6  |      | g                  |  |                       |        |
| Case Isolation Voltage     | $V_{isol}$  | 4.3  |      |      | kV                 | DC, $t = 1\text{ s}$                       |                       |        |
| Comparative Tracking Index | CTI         | 600  |      |      |                    |  |                       |        |
| Creepage Distance          |             | 6.3  |      |      | mm                 | Terminal to thermal pad                    |                       |        |

Note (3): Total effective resistance = MOSFET  $R_{DS(on)}$  + package resistance

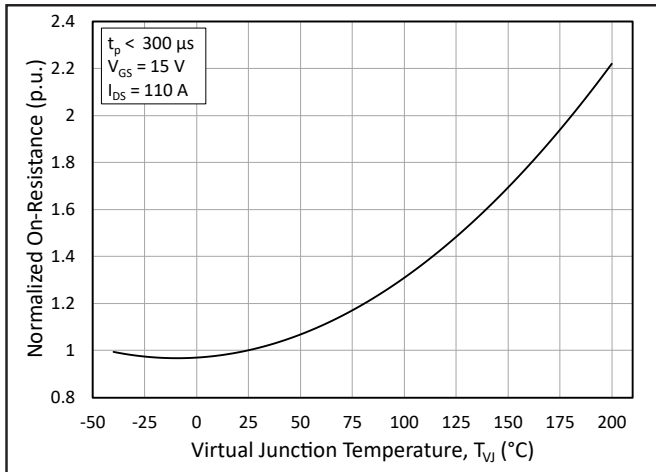
## Typical Performance



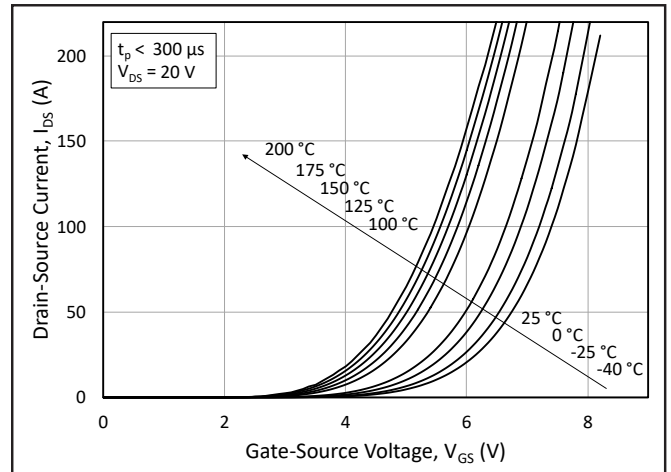
**Figure 1.** Output Characteristics for Various Junction Temperatures



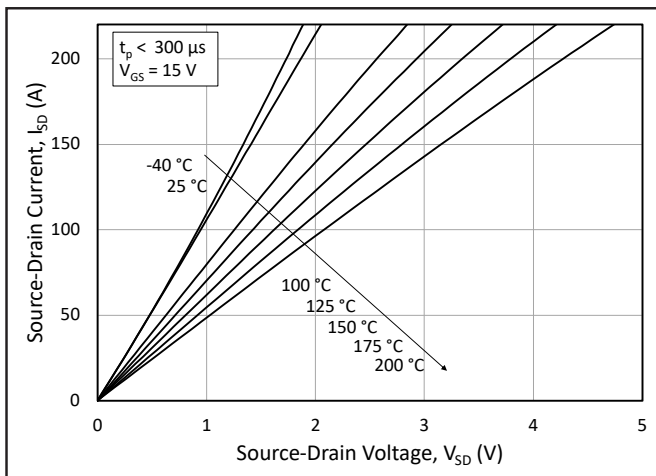
**Figure 2.** Normalized On-State Resistance vs. Drain Current for Various Junction Temperatures



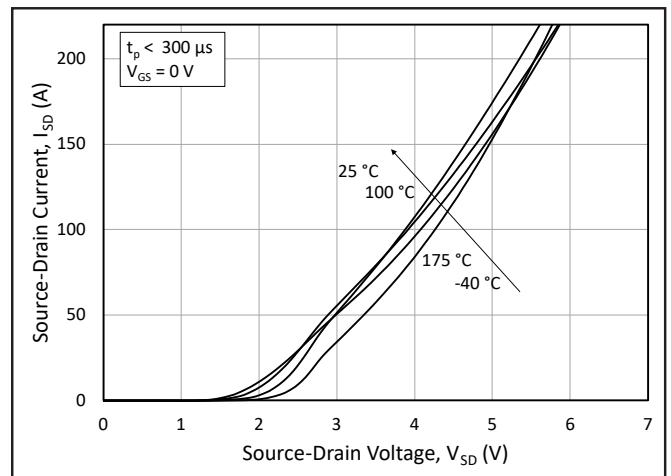
**Figure 3.** Normalized On-State Resistance vs. Junction Temperature



**Figure 4.** Transfer Characteristic for Various Junction Temperatures



**Figure 5.** 3<sup>rd</sup> Quadrant Characteristic vs. Junction Temperatures at  $V_{GS} = 15\text{ V}$



**Figure 6.** 3<sup>rd</sup> Quadrant Characteristic vs. Junction Temperatures at  $V_{GS} = 0\text{ V}$  (Body Diode)



Typical Performance

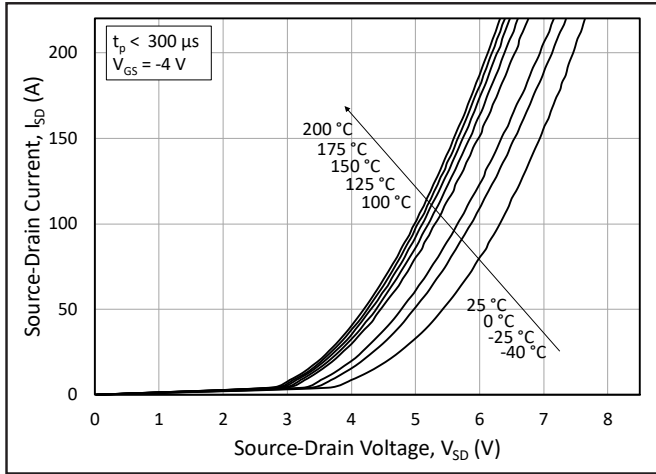


Figure 7. 3<sup>rd</sup> Quadrant Characteristic vs. Junction Temperatures at  $V_{GS} = -4$  V (Body Diode)

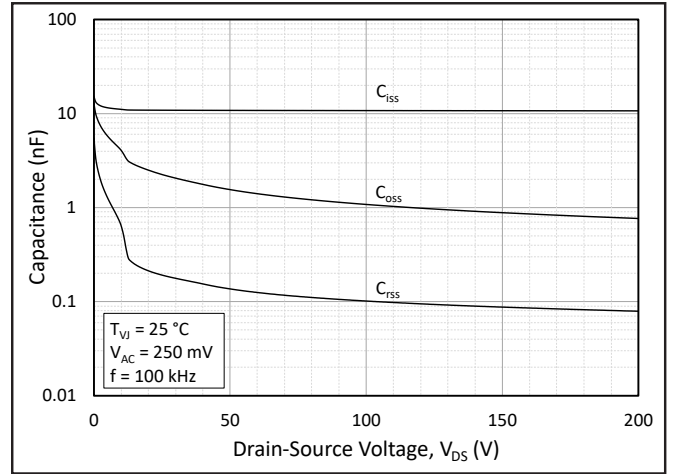


Figure 8. Typical Capacitances vs. Drain to Source Voltage (0 - 200 V)

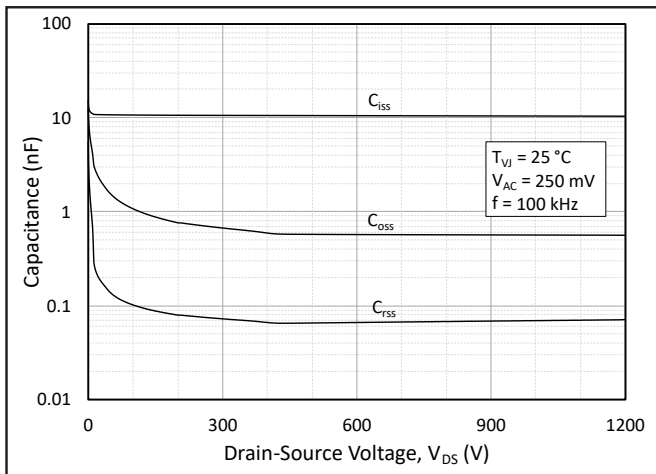


Figure 9. Typical Capacitances vs. Drain to Source Voltage (0 - 1200V)

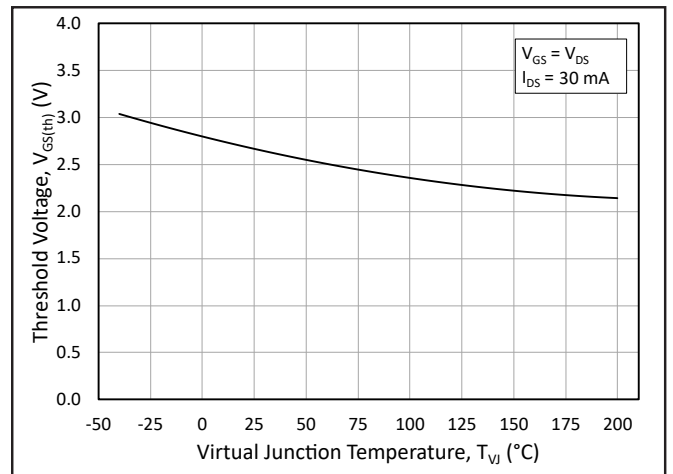


Figure 10. Threshold Voltage vs. Junction Temperature

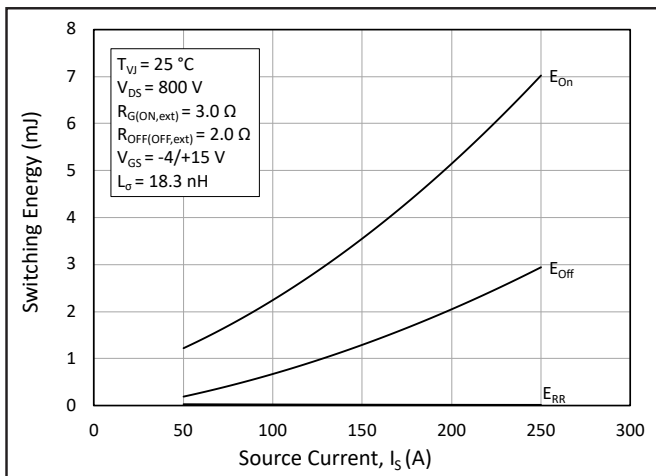


Figure 11. Switching Energy vs. Drain Current ( $T_{vj} = 25$  °C)

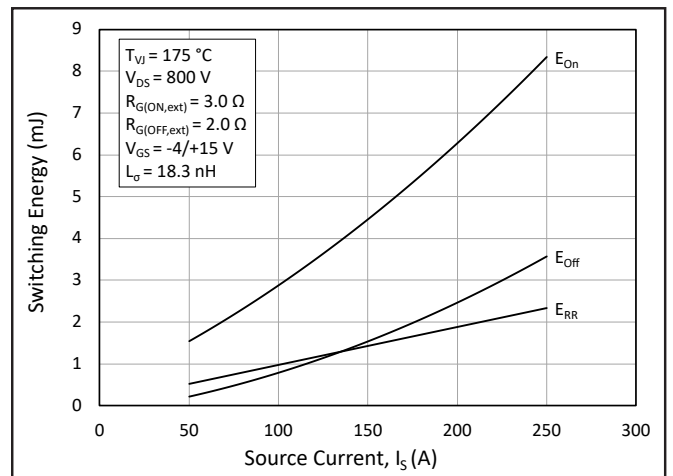


Figure 12. Switching Energy vs. Drain Current ( $T_{vj} = 175$  °C)



Typical Performance

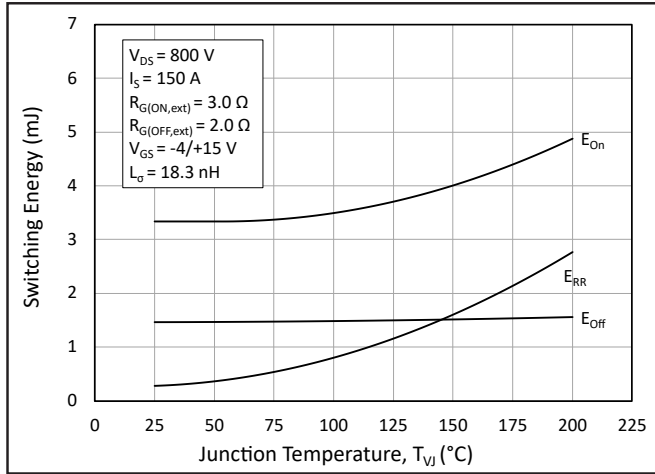


Figure 13. Switching Energy vs. Junction Temperature

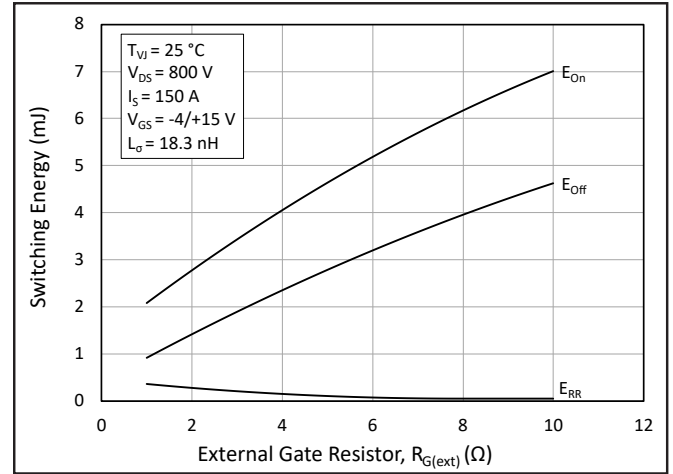


Figure 14. Switching Energy vs. External Gate Resistance

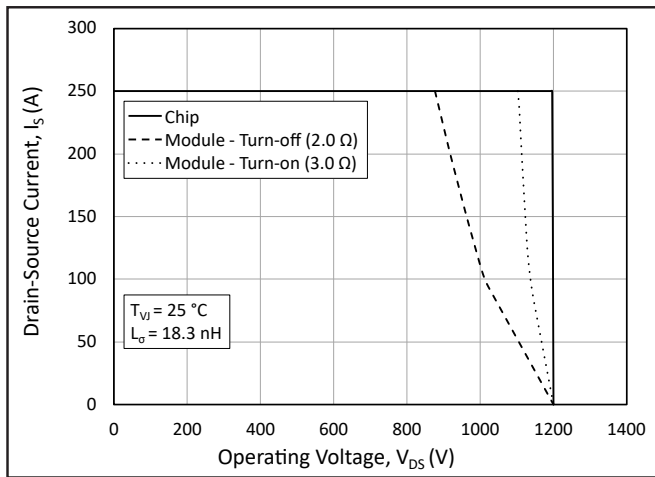


Figure 15. Switching Safe Operating Area

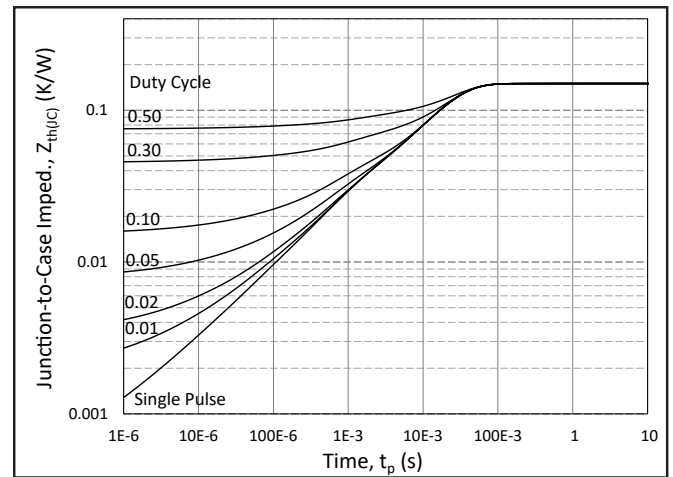


Figure 16. Junction to Case Transient Thermal Impedance

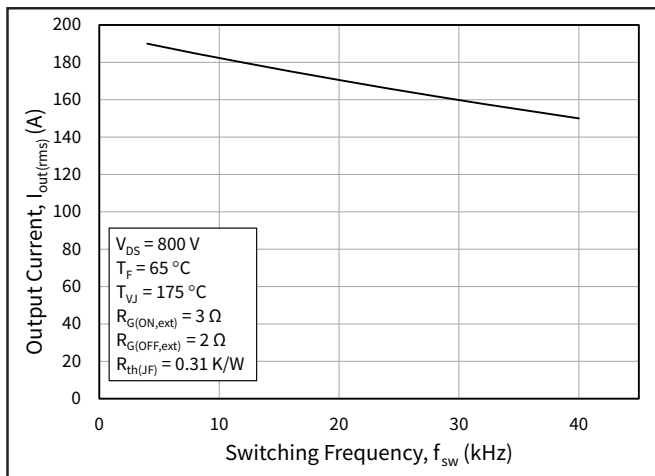
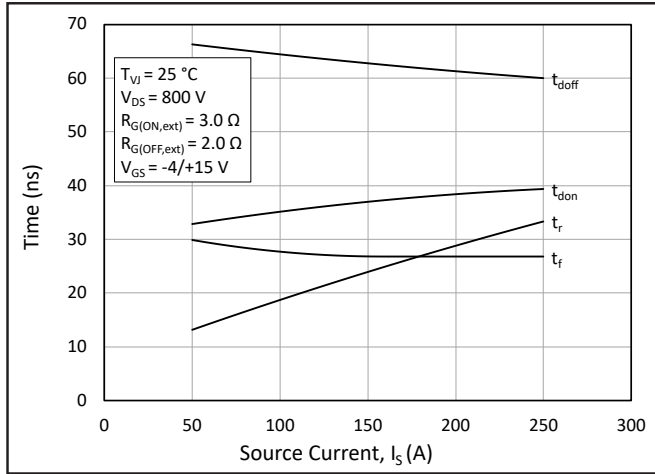


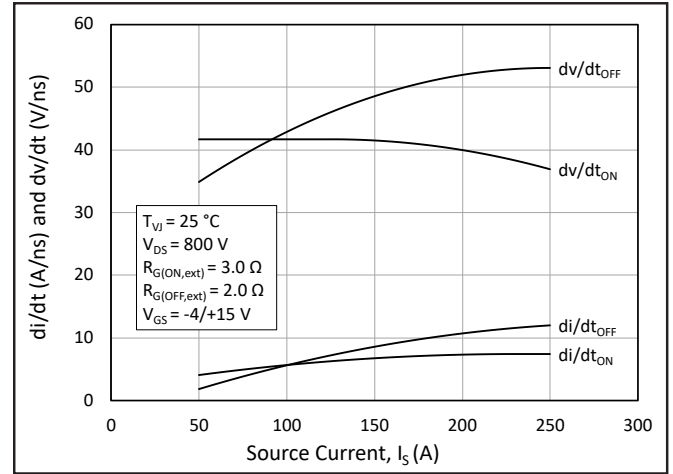
Figure 17. Typical Output Current Capability vs. Switching Frequency (Inverter Application)



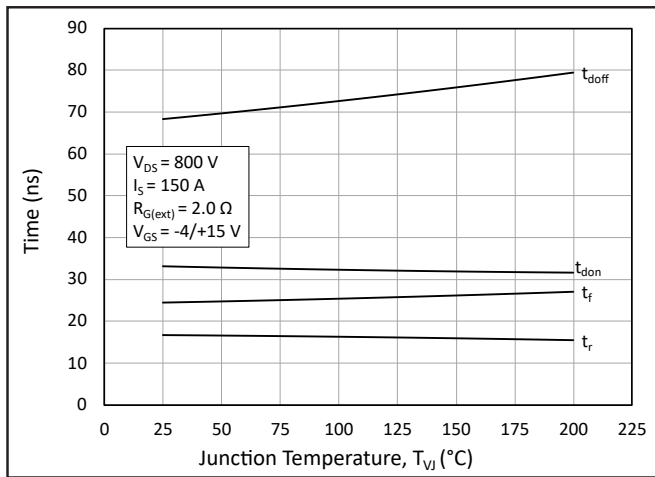
## Timing Characteristics



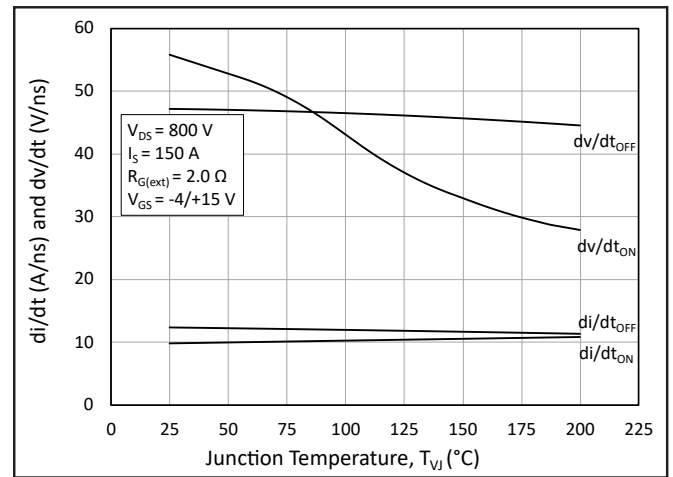
**Figure 18.** Timing vs. Source Current



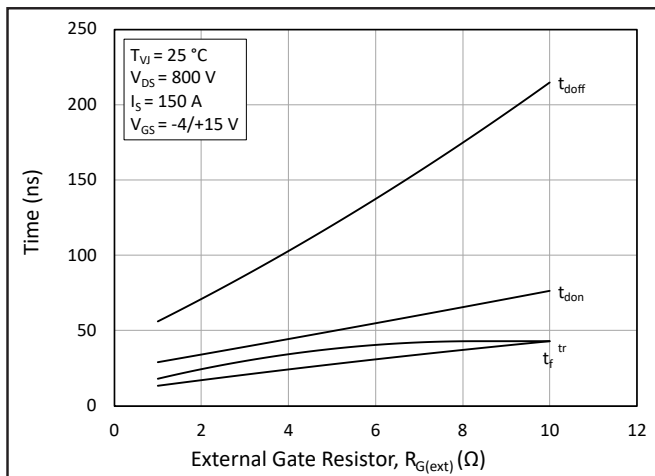
**Figure 19.** dv/dt and di/dt vs. Source Current



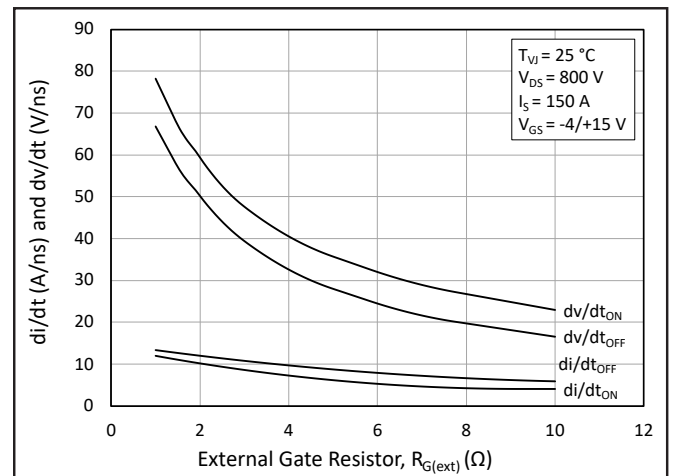
**Figure 20.** Timing vs. Junction Temperature



**Figure 21.** dv/dt and di/dt vs. Junction Temperature

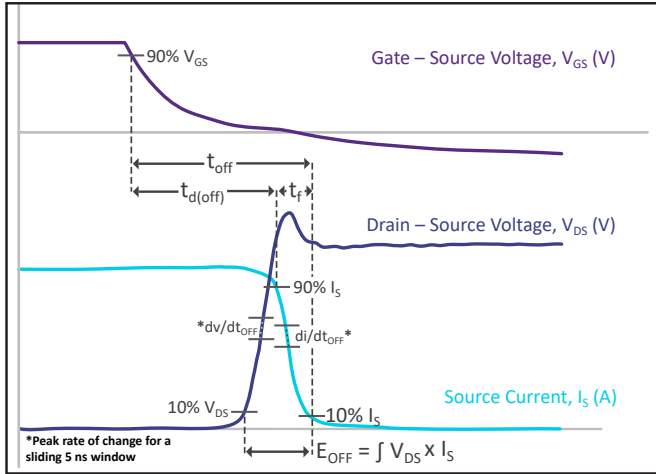


**Figure 22.** Timing vs. External Gate Resistance

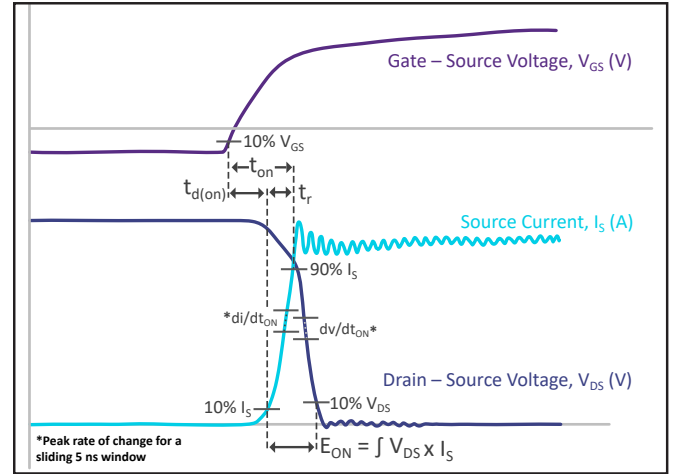


**Figure 23.** dv/dt and di/dt vs. External Gate Resistance

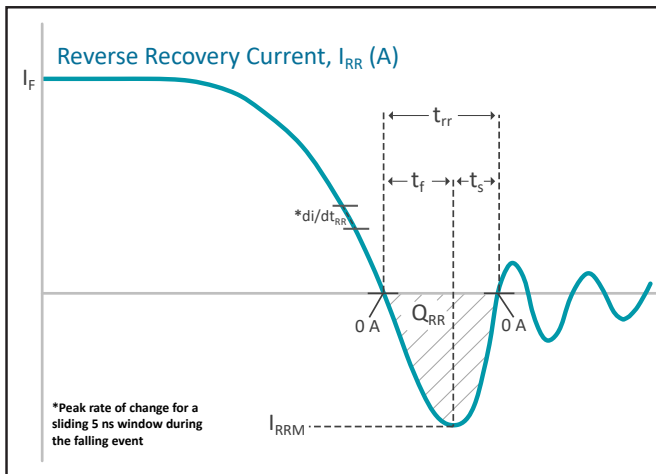
**Definitions**



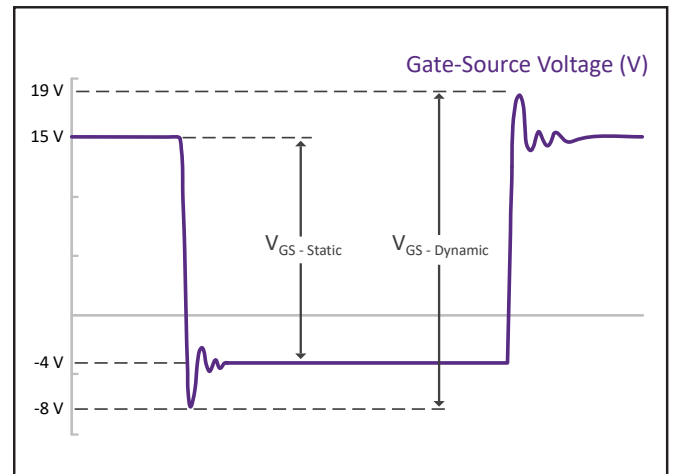
**Figure 24. Turn-Off Transient Definitions**



**Figure 25. Turn-On Transient Definitions**

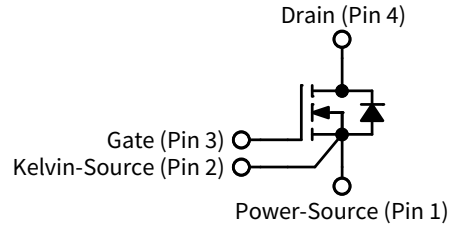
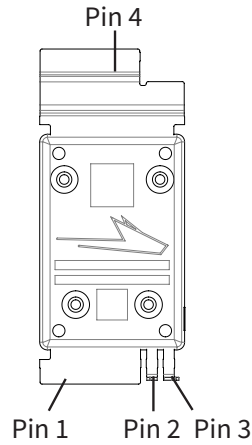


**Figure 26. Reverse Recovery Definitions**



**Figure 27.  $V_{GS}$  Transient Definitions**

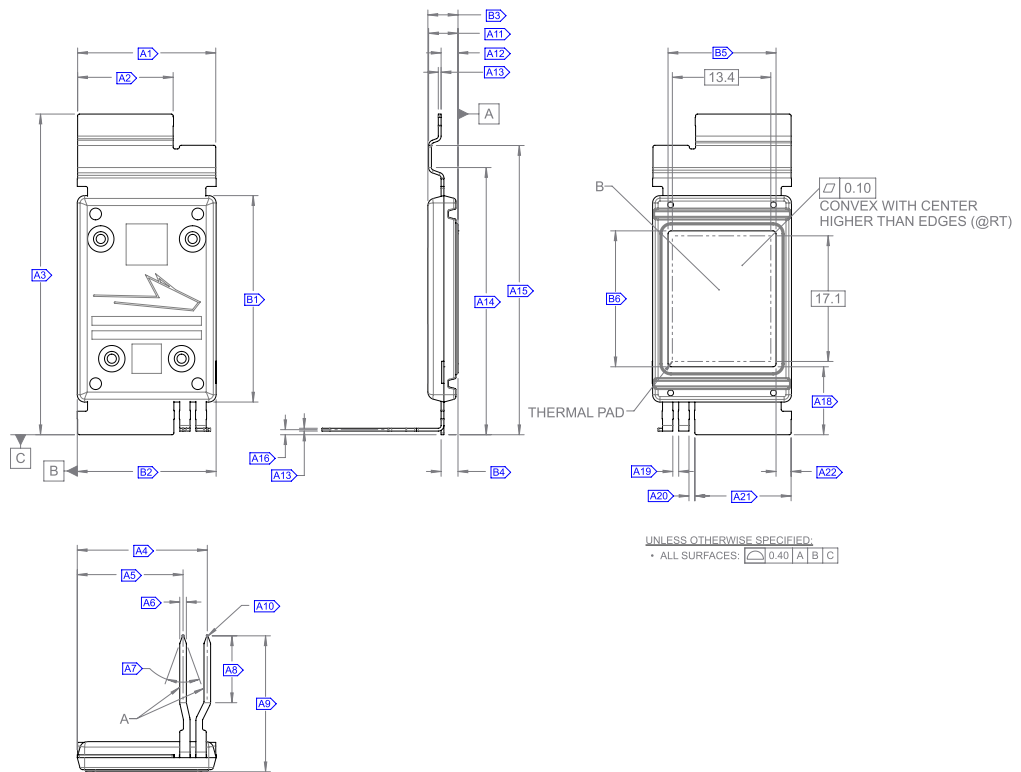
### Schematic and Pin Out



### Package Dimensions (mm)

| DIMENSION TABLE |   |
|-----------------|---|
| SYM.            | DIMENSION/TOLERANCE   |
| A1              | 18.8±0.20   |
| A2              | 13±0.20   |
| A3              | 43.65±0.30  |
| B1              | 28.1±0.20   |
| B2              | 18.9±0.30   |
| A4              | 17.7±0.40   |
| A5              | 14.4±0.40   |
| A6              | 2× 0.9±0.10   |
| A7              | 2× [40°]  |
| A8              | [9.1] - Short pin version<br>9.6 - Long pin version           |
| A9              | 18.5±0.50 - Short pin version<br>19.0±0.50 - Long pin version |
| A10             | 2× R0.1±0.10  |
| B3              | 4.1±0.10  |
| A11             | 4±0.30  |
| A12             | 2.3±0.30  |
| A13             | [0.381]   |
| A14             | 36.37±0.30  |
| A15             | 39.37±0.30  |
| A16             | 0.69±0.65   |
| B4              | 2.3±0.30  |
| B5              | [14.7]  |
| B6              | [18.5]  |
| A17             | 9.5 MAX   |
| A18             | [0.8]   |
| A19             | [0.8]   |
| A20             | [0.8]   |
| A21             | 13.1±0.20   |
| A22             | 2.3 MAX   |

| NOTE |                         |
|------|-------------------------|
| A    | Ag Plating, Signal Pins |
| B    | Ag Plating, Thermal Pad |





## Product Ordering Code

| Part Number   | Description                             |
|---------------|---|
| EDB010M12TM4  | Short gate and Kelvin-source pin length |
| EDB010M12TM4L | Long gate and Kelvin-source pin length  |

## Revision History

| Revision History | Date          | Brief Summary   |
|------------------|---------------|-----------------|
| Rev. 1           | October 2025  | Initial release |
| Rev. 2           | December 2025 | Updated drawing |

## Supporting Links & Tools

### Evaluation Tools & Support

- [PLECS Circuit Model](#)
- 3D CAD Model
- FEA Thermal Model - Available Upon Request
- KIT-CRD-CIL-12N-TMA: Dynamic Performance Evaluation Kit for TM Power Modules

### Application Notes

- [PRD-04814: Design Options for Wolfspeed® Silicon Carbide MOSFET Gate Bias Power Supplies](#)
- [PRD-06379: Environmental Considerations for Power Electronics Systems](#)
- [PRD-08333: Wolfspeed Module CIL Evaluation Kits User Guide](#)
- [PRD-08376: Thermal Characterization Methods and Applications](#)
- [PRD-08710: Measuring Stray Inductance in Power Electronics Systems](#)
- [PRD-08911: Considerations for Current Balancing in Paralleled SiC Power Modules](#)



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REACH substances of high concern (SVHCs) information is available for this product. Since the European Chemical Agency (ECHA) has published notice of their intent to frequently revise the SVHC listing for the foreseeable future, please contact your Wolfspeed representative to ensure you get the most up-to-date REACH SVHC Declaration. REACH banned substance information (REACH Article 67) is also available upon request.

### **Contact info:**

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